

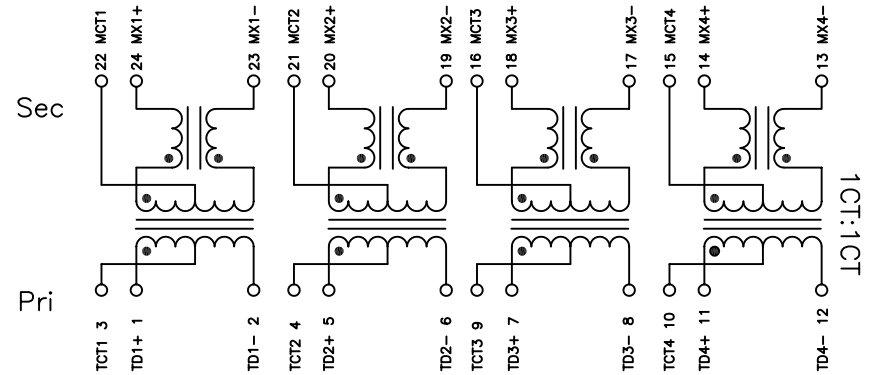
SUGGESTED PAD LAYOUT

Method 208H for solderability.

2. Flammability: UL94V-0
3. ASTM oxygen index: > 28%
5. All listed parameters are to be within tolerance from -40C to +85C unless otherwise noted.
6. Storage
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC. REV: B/1

2. Schematic:



3. Electrical Specifications: @25°C

- Pri OCL: 350uH Min @100KHz 0.1V 8mA
- Pri OCL: 280uH Min @100KHz 0.1V 8mA at -40C
- Q: 5 Min @10KHz 50mV
- Pri LL: 0.4uH Max @100KHz 0.1V (short Sec)
- Cw/w: Pri-Sec 15pF Typ @100KHz 0.1V
- Pri DC Res: 1.3 Ohms Max
- Insertion Loss: -1.1dB Max 1MHz-100MHz
- Return Loss: -18dB Typ 1-40MHz
 - 14dB Typ 40-60MHz
 - 12dB Typ 60-80MHz
 - 7dB Typ 80-100MHz
- Cross Talk: -40dB Min 1MHz-100MHz

Turns Ratio: 1CT:1CT±3%

Hipot: 1500Vrms Pri to Sec

XFMRS Inc www.XFMRS.com	Title: 1000BASE-T Modules		
	UNLESS OTHERWISE SPECIFIED	P/N: XFGIA100J	REV. B
TOLERANCES:	DWN.	Feng	Sep-22-11
.xxx ±0.010	CHK.	YK Liao	Sep-22-11
Dimensions in Inch	APP.	BW	Sep-22-11
SHT 1 OF 1			